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App. No. 10/681,833

PATENT

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS

Application No.: 10/681,833

Filed: October 8, 2003

Title: **Semiconductor stacked multi-package
module having inverted second package
and electrically shielded first package**

)
) Examiner: Pershelle L. GREENE
)
) Group Art Unit: 2826
)
) Date: November 1, 2004

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: Mail Stop Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 1, 2004.

Signed

Paula Faulk Hurley

MAIL STOP AMENDMENT
COMMISSIONER FOR PATENTS
P.O BOX 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed June 30, 2004, kindly amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

There are no amendments to the claims. A **Listing of Claims** is included for the Examiner's convenience, beginning on page 5 of this paper.

Amendments to the Drawings begin on page 9 of this paper and include both attached replacement sheets and annotated sheets showing changes.

Remarks begin on page 10 of this paper.

An **Appendix** including amended drawing figures is attached following page 15 of this paper.